

MARKED-UP PREVIOUS VERSION OF THE AMENDED CLAIM

1. (Thrice Amended) An electrically tested electronic device, free from infantile mortality, for direct mounting on a printed circuit board, wherein said electronic device comprises a silicon die having a top surface, a bottom surface, and four side edges, in which an integrated circuit is realized externally accessible through a plurality of connection pads and an array of connection pins which are mechanically and removably connected to said silicon die by connection means for removable attachment of said pins, and are electrically connected to the connection pads of said silicon die by electric connection means, said electronic device being unpackaged or partially packaged in a resin, wherein each of said connection pins includes a first end [pre-formed] portion and a second end portion and a bend portion formed between said first and second portions, [which] with said bend portion [is] not being encapsulated in said resin, in order to accommodate the thermal expansion difference between the silicon die and a printed circuit board on which said electronic device is mounted.

: UN-PACKAGED OR SEMI-PACKAGED
ELECTRICALLY TESTED
Applicant: Francesco BETORI
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